

b) Amendments to the Claims

Please amend claims 1-3 and 6-9 as follows. A detailed listing of all claims which are or were in this application is provided.

--1. (Currently Amended) A deposited-film formation apparatus for forming a deposited film on a substrate by:

generating plasma in a discharge space defined between a power-applying electrode and the substrate in a vacuum chamber; the substrate ~~being servable~~ acting as an electrode disposed opposingly to the power-applying electrode; and

decomposing a material gas fed into the vacuum chamber, wherein;

the substrate has a flexibility, and the power-supplying electrode is provided with an undulation on its surface on the side of the discharge space in such a way that the distance between the substrate and the power-applying electrode ~~comes to be~~ is a desired value in agreement with ~~the curving~~ a curvature of the substrate.

2. (Currently Amended) The deposited-film formation apparatus according to claim 1, wherein the undulation is formed in agreement with the ~~curving~~ curvature of the substrate in the course of its transportation.

3. (Currently Amended) A deposited-film formation apparatus for forming a deposited film on a substrate by;

generating plasma in a discharge space defined between a power-applying electrode and the substrate in a vacuum chamber, the substrate ~~being servable~~ acting as an electrode disposed opposingly to the power-applying electrode; and

decomposing a material gas fed into the vacuum chamber; wherein;

the power-applying electrode has a structure comprising a plurality of sheets or a plurality of columnar members which are bundled upright with respect to the substrate.

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4. (Original) The deposited-film formation apparatus according to claim 3, wherein the substrate has a flexibility, and the power-applying electrode is an electrode which is pressed against the surface of the substrate in such a way that individual sheets or individual columnar members constituting the power-applying electrode come into contact with that surface at their upper ends so that a curved shape of the substrate is transferred to the surface of the power-applying electrode.

5. (Original) The deposited-film formation apparatus according to claim 3, wherein a means for pressing the power-applying electrode against the surface of the substrate in such a way that individual sheets or individual columnar members constituting the power-applying electrode come into contact with that surface is further provided at the power-applying electrode on its side opposite to the substrate side.

6. (Currently Amended) The deposited-film formation apparatus according to claim 3, which has a mechanism for transporting the substrate and wherein the surface that connects substrate-side ends of the plurality of sheets or plurality of columnar members is so formed as to be in agreement with the curving curvature of the substrate in the course of its transportation.

7. (Currently Amended) A deposited-film formation process comprising the steps of:

generating plasma in a discharge space defined between a power-applying electrode and the substrate in a vacuum chamber, the substrate ~~being servable~~ acting as an electrode disposed opposingly to the power-applying electrode; and decomposing a material gas fed into the vacuum chamber, to form a deposited film on the substrate which the substrate is transported,

wherein;

the process further comprises the steps of:

providing the power-applying electrode with an undulation on its surface in agreement with the curving curvature of the substrate in the course of its transportation; and

disposing the power-applying electrode in the vacuum chamber.

8. (Currently Amended) A deposited-film formation process comprising the steps of:

generating plasma in a discharge space defined between a power-applying electrode and the substrate in a vacuum chamber, the substrate ~~being servable~~ acting as an electrode disposed opposingly to the power-applying electrode, and decomposing a material gas fed into the vacuum chamber, to form a deposited film on the substrate

wherein;

the inside of the vacuum chamber is brought into conditions for forming the deposited film, and the deposited film is formed by generating the plasma after the power-applying electrode, constituted of a plurality of sheets or a plurality of columnar members which are bundled upright with respect to the substrate, is so pressed against the substrate as to come into contact with its surface to transfer a curved shape of the substrate to the surface of the power-applying electrode and then the power-applying electrode is separated from the surface of the substrate.

9. (Currently Amended) A deposited-film formation apparatus comprising:

(a) a power-applying electrode and a flexible substrate in a vacuum chamber;

(b) a discharge space between the power-applying electrode and the flexible substrate; and

(c) a material gas fed into the vacuum chamber;

wherein the substrate ~~can serve~~ acts as an electrode disposed opposing the power-applying electrode and wherein the power-applying electrode has an undulation on its surface on the

side of the discharge space such that the distance between the substrate and the power-applying electrode is a predetermined value in accordance with the curvature of the substrate.--

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